

6/25/04

	L #	Hits	Search Text	DBs
1	L1	2651	(microlens\$4 or (micro adj lens\$4) or (array near3 lens\$4) or lenslet).ti,ab.	USPA T; US-PG PUB
2	L2	4914	(bond\$4 adj pad or scribe).ti,ab.	USPA T; US-PG PUB
3	L3	13	1 and 2	USPA T; US-PG PUB
4	L4	25061	(resist or photoresist).ti,ab.	USPA T; US-PG PUB
5	L6	61	1 and 4	USPA T; US-PG PUB
6	L7	32625 4	(wafer or semiconductor or image or imaging).ti,ab.	USPA T; US-PG PUB
7	L8	1307	1 and 7	USPA T; US-PG PUB
8	L9	11282 0	fill\$4.ti,ab.	USPA T; US-PG PUB
9	L10	34	8 and 9	USPA T; US-PG PUB
10	L11	2856	430/321,330.ccls.	USPA T; US-PG PUB
11	L12	56	1 and 11	USPA T; US-PG PUB
12	L13	40	12 not (3 or 6 or 10)	USPA T; US-PG PUB
13	L14	94	1 and 9	USPA T; US-PG PUB

	L #	Hits	Search Text	DBs
14	L15	60	14 not 10	USPA T; US-PG PUB
15	L16	2296	topograph\$6.ti,ab.	USPA T; US-PG PUB
16	L17	6	1 and 16	USPA T; US-PG PUB
17	L19	6408	indent\$6.ti,ab.	USPA T; US-PG PUB
18	L20	5	1 and 19	USPA T; US-PG PUB
19	L21	14110	microlens\$4 or (micro adj lens\$4) or (array near3 lens\$4) or lenslet	EPO; JPO; DERW ENT; IBM_T DB
20	L22	17778 1	resist or photoresist	EPO; JPO; DERW ENT; IBM_T DB
21	L23	20418	bond\$4 adj pad or scribe	EPO; JPO; DERW ENT; IBM_T DB
22	L24	15	21 and 22 and 23	EPO; JPO; DERW ENT; IBM_T DB
23	L25	79737 1	fill\$4	EPO; JPO; DERW ENT; IBM_T DB

	L #	Hits	Search Text	DBs
24	L26	25	21 and 22 and 25	EPO; JPO; DERW ENT; IBM_T DB
25	L27	6330	topograph\$6	EPO; JPO; DERW ENT; IBM_T DB
26	L28	2	21 and 22 and 27	EPO; JPO; DERW ENT; IBM_T DB
27	L29	28223 55	wafer or semiconductor or image or imager or imaging	EPO; JPO; DERW ENT; IBM_T DB
28	L30	302	21 and 22 and 29	EPO; JPO; DERW ENT; IBM_T DB
29	L31	15255 79	(planar\$6 or level\$4 or flat or flatten\$6).ti,ab.	EPO; JPO; DERW ENT; IBM_T DB
30	L32	77	30 and 31	EPO; JPO; DERW ENT; IBM_T DB